

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	("6548121").PN.	USPAT; USOCR	OR	OFF	2009/02/19 16:58
S2	1180	"ciba specialty chemicals corporation".as.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:03
S3	5	"ciba specialty chemicals corporation".as. and strongly adherent coatings	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:04
S4	5	"ciba specialty chemicals corporation".as. and strongly adherent coating	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:04
S5	1	10/566743.app.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:37
S6	1	("7455891").PN.	USPAT; USOCR	OR	OFF	2009/02/20 11:00
S7	8	((("7455891") or ("6251963") or ("6486228") or ("6515051") or ("6803392") or ("6733847") or ("6548121") or ("6368362"))).PN.	USPAT; USOCR	OR	OFF	2009/02/20 11:09
S8	9	((("7455891") or ("6251963") or ("6486228") or ("6515051") or ("6803392") or ("6733847") or ("6548121") or ("6368362") or ("6399805"))).PN.	USPAT; USOCR	OR	OFF	2009/02/20 11:14
S9	108	("3669951" "3936305" "4082679" "4199421" "4226763" "4246315" "4275004" "4278589" "4292152" "4298738" "4315848" "4324744" "4347180" "4385109" "4466993" "4533652" "4567106" "4681905" "4684679" "4684680" "4710523" "4737593" "4792632" "4861916" "4868246" "4965294" "4990364" "5053246" "5080994" "5106891" "5108835" "5116534" "5153284" "5166355" "5168087" "5196142" "5218009" "5250698" "5252403" "5278314" "5280124" "5292890" "5330539" "5360850" "5399770" "5436349" "5456728" "5472992" "5504236" "5516914" "5549847" "5554760" "5563242" "5574166" "5607987" "5646088" "5935900" "5942290" "5955514" "5990189" "6099122" "6190423" "6329445" "6344505" "6361925" "6376065" "6399805" "6407254" "6548121" "6733847").PN. OR ("6251963" "6368362" "6399805" "6486228" "6515051" "6548121" "6733847" "6803392" "7455891").URPN.	US-PGRUB; USPAT; USOCR	ADJ	ON	2009/02/20 11:21
S10	15	("4199421" "4246315" "4466993" "4567106" "4990364" "5053246" "5252403" "6099122" "6548121" "6733847").PN. OR ("6548121" "6733847" "7455891").URPN.	US-PGRUB; USPAT; USOCR	ADJ	ON	2009/02/20 11:22
S11	21169	427/533,535,536,517,407.1-412.5,532-559,517,509,512,513,517,518,519,520,535,536,538,551,553,554,556,407.2,409,412,412.1,419.2.ccls. or 430/311.ccls.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 11:27

S12	5299	427/533,509.ccls. or 430/311.ccls.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 11:27
S13	211	(adhere\$4 or adhesion or glu\$3 or bond\$3) with metallized with (organic or polymer) with substrate	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S14	139	(adhere\$4 or adhesion or glu\$3 or bond\$3) with metallized with (organic or polymer) with substrate and @PY< "2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S15	13	(adhere\$4 or adhesion or glu\$3 or bond\$3) with metallized with (organic or polymer) with substrate and @PY< "2004" and S11	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S16	7	circuit and photoinitiator with adhesion with metal	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 16:56
S17	183	circuit and photoinitiator with adhesion and (metal or copper)	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:11
S18	13	circuit and photoinitiator with adhesion with (metal or copper)	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:11
S19	613	circuit and photoresist with adhesion with (metal or copper)	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:18
S20	283	circuit and photoresist with adhesion with (metal or copper) and plasma	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:18
S21	47	circuit and photoresist with adhesion with (metal or copper) with plasma	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:19

S22	0	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) with adhesion with (metal or copper) with plasma	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:34
S23	0	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) and adhesion with (metal or copper) with plasma	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:34
S24	1116	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV)	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:35
S25	46	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) with adhesion	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:35
S26	10	solder mask with UV with adhesion	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:40
S27	2	"20030129322".did.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:42
S28	13	solder mask with (cvd or evaporate or pvd)	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:38
S29	692	solder with (cvd or evaporate or pvd)	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:41
S30	5	solder with (cvd or evaporate or pvd) with (photopolymerizable or UV or photoinitiator or photoresist)	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:43
S31	149	solder with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist)	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44

S32	12645	metal with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist)	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
S33	45	solder with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
S34	580	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:57
S35	25	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) with (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:57
S36	3	wiring board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) with (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:58
S37	121	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004" and cmp	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 19:05
S38	1	("6524950").PN.	USPAT; USOCR	OR	OFF	2009/02/20 19:21
S39	600	photoresist with (lift off or liftoff) and polymer\$2 with substrate and metal	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:24
S40	189	photoresist with (lift off or liftoff) and polymer\$2 with substrate and metal and @PY<"2003"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:24
S41	12	photoresist with (lift off or liftoff) and polymer\$2 with substrate and metal and develop\$3 with (solvent or mechanical\$3)and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY<"2003"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:25
S42	0	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop\$3 with (solvent or mechanical\$3)and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY<"2003"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34

S43	0	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop\$3 with (solvent or mechanical\$3)and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
S44	73	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop\$3 and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
S45	1721	(lithography or photoresist) with (lift off or liftoff) and (polymer\$2 or metal\$3 or glass or metal oxide) with substrate and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 13:42
S46	132	(lithography or photoresist) with (lift off or liftoff) and (polymer\$2 or metal\$3 or glass or metal oxide) with substrate and (sputter or evaporate) with (metal or half-metal) and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 13:43
S47	265	427/98.5.ccls.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 14:01
S48	95	427/98.5.ccls. and (resist or photoinitiator)	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 14:02
S49	26	427/98.5.ccls. and (resist or photoinitiator) and plasma	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 14:03
S50	2	10/502208.app.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 15:36

2/24/2009 12:27:55 PM

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